Channel Talk

FEBRUARY 2022

SERVING YOU

Laird, finishing a strong 2021, has our sights set on added growth and still more innovation this year. Our momentum is growing as one of the newest members of the DuPont family of businesses. We continue working more closely with you than ever. With sales support. With a bigger digital marketing footprint. With other aids to help you elevate your success. New products and new ideas keep flowing. Laird is committed to supporting your team so that together we can enable and protect high performance products like no one else. Read what we have newly introduced to help you grow.

Channel Talk is our bi-monthly outreach dedicated to your success.



MULTI-FUNCTIONAL GRAPHITE OVER FOAM GASKET

Laird has identified at least 25 industries or OEM product sectors primed to fill large gaps in designs



using GOF3000[™], our new thermally and electrically conductive EMI graphite-over-foam gasket. GOF3000 provides thermal conductivity in the form of a traditional wrapped compressible foam gasket, along with an outside wrap for electrical conductivity. This gasket combines the thermal transfer performance of Laird's Tgon[™] 9000 synthetic graphite outside wrap and the repeatable compression and rebound of the foam core. GOF3000 utilizes a silicone foam core for lower compression force and UL VO flammability rating. See the datasheet and get your sample.

LOWEST THERMAL **RESISTANCE ON THE MARKET**

Tpcm[™] 7000 is the newest entry in the line of high-performance thermal interface material offerings.

With a thermal conductivity of 7.5 W/mK, Tpcm 7000 is designed to enhance the cooling of the most rigorous thermal challenges in electronics. Coupled with superior wetting of the mating surfaces and displacing air, Tpcm 7000 provides industryleading lowest thermal resistance. Tpcm 7000 has demonstrated its reliability through exposure to 2000 hours of various aging tests at an operating temperature of 150°C. See the datasheet and order a sample now.

RESOLUTION ROUNDTABLE ON TAP

Get set for 2022's return of our popular Field Application Engineer Resolution Roundtable series. Hundreds view these videotaped programs. In them, Laird teams

gather to share insights and ideas, focusing in depth on some of the toughest electronic protection obstacles they have faced. They cover automotive, consumer products, data infrastructure, health care and more. Look for the announcement soon.



PANEL TOPS TRADITIONAL **ALUMINUM HONEYCOMB**

End the worry over damaged or deformed vent panels made



of aluminum honeycomb. Laird's 5G MaxAir[™] is made of an aluminum metallized polycarbonate honeycomb. The new vent panel offers a dent-resistant and durable rigid structure and flexibility along with a frameless design. It enables an easy, press-fit installation too. Use 5G MaxAir to increase air flow, shield EMI, and protect data center equipment including servers. routers, switches and storage units. Halogen free and flame retardant, 5G MaxAIr weighs approximately 50 percent less than a traditional metallic honeycomb panel. See the **datasheet** for more details.

INSIGHTS ENGINEERED VIDEO

Don't miss the next Insights Engineered, Laird's on-demand video series. Laird experts bring you and your customers closer to



challenges and successes and place special emphasis on trends. In this examination, "Making the Most of the Transition to 5G," hear from Staff Scientist Paul Dixon and Europe's Matt Tapping, who join host and Laird R&D Leader Ethan Simon. Watch the 18-minute video now and share it liberally.

WIRE WOUND CERAMIC **CHIP INDUCTOR**

OEMs clear many roadblocks before the ultimate success of a design. Our new low profile, compact, and reliable IWC Series SMD wire wound



ceramic chip inductors more efficiently mitigate signal interference to accomplish that goal. They deliver high Q factor and low loss. Telecom, industrial, and general consumer electronics design engineers will find the inductor's high resonance frequency an aid to improving circuit performance. The series offers inductor thicknesses ranging from 0.66 mm to 2.23 mm, providing added design flexibility.





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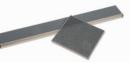
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